## UV-NIL with a DUV-Fabricated Silicon Template as a Flexible Tool for Nanopatterning

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UV-based nano-imprint lithography (UV-NIL) is a very promising technique for rapid and large-scale patterning at very high resolution and at low cost [1]. UV-NIL is performed under low pressures (< 1 bar) and does not need thermal cycles. Moreover, the use of a transparent stamp offers the advantage of precision alignment. Therefore, UV-NIL offers a cheap and flexible technology for sub-micron patterning and is of high interest not only for very demanding applications such as micro-electronics and photonics but also for a variety of research and industrial applications such as in chemistry and biotechnology.

Getting access to nanostructured stamps is not straight-forward and rather expensive. E-beam lithography is needed to attain the high-resolution and often also silica etching is required. However, the technology for silica etching is not as mature as for silicon etching and therefore, resources for very high-resolution silica etching are rather limited. Moreover, the long writing times typical for e-beam lithography are a limiting factor for fabricating very large areas of nanopatterns in the laboratory.

We demonstrate that nanostructured silicon chips made by standard mass-production technologies, in particular deep-UV lithography, used for the fabrication of very large scale integrated (VLSI) electronic circuits CMOS fabrication, can as well be used as templates for fabricating transparent stamps suitable for UV-NIL. The fabrication scheme itself - also based on UV-NIL - is easy-to-implement, does not require accurate control of the applied pressure and should be expandable to a wafer-scale process. The fabrication scheme is schematically shown in Fig. 1. First the silicon chip is treated to prevent adhesion. Then a drop of a commercially available nano-imprint resist (PAK-01, *Toyo Gosei Co.*) is squeezed between the silicon chip and a glass substrate, so that the polymer gets imprinted. After UV-curing through the glass substrate and removal of the silicon chip, the transparent two-layer UV-NIL stamp is ready. Fig. 2 shows the result.

We demonstrate the use of such a stamp for gold nanopatterning on top of silicon. Gold is a very interesting chemically inert material for immobilization of biomolecules and the investigation of gold nanopatterns for applications in chemistry and biotechnology is an important challenge. A resist drop of very low viscosity based on a mixture of benzylmethacrylate and poly-dimethyl-siloxane is squeezed between the silicon substrate and the UV-NIL stamp. Next, the resist is cured by UV illumination through the stamp and the stamp is removed. A short oxygen plasma etch removes the residual layer. After evaporating gold the patterns are defined by lift-off. Fig. 3 shows images of the various fabricated gold micro- and nanopatterns. They are all fabricated in the same single step.

These results illustrate that very high-resolution patterns over very large areas can be obtained starting from a nanostructured silicon template fabricated by standard technologies. The described UV-NIL processes are easy-to-implement in a laboratory environment and allow for a flexible choice of materials offering a cheap nano-imprint method to be used for a variety of applications including fabrication of nanopatterned substrates which can be used for immobilization of biomolecules.

[1] M. Bender, M. Otto, B. Hadam et al., "Multiple imprinting in UV-based nanoimprint lithography: related material issues", *Microelectronic Engineering*, vol. 61-62, pp. 407-413, 2002.

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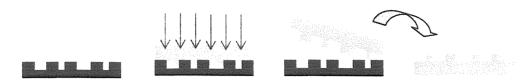


Figure 1. Fabrication scheme of a UV-NIL stamp starting from a silicon template.

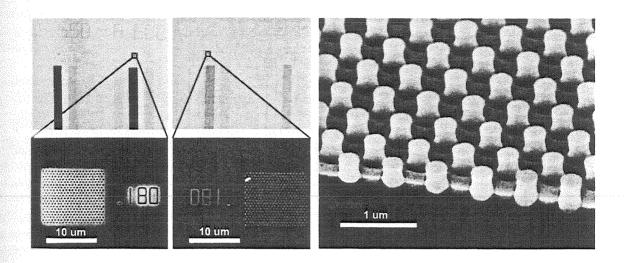
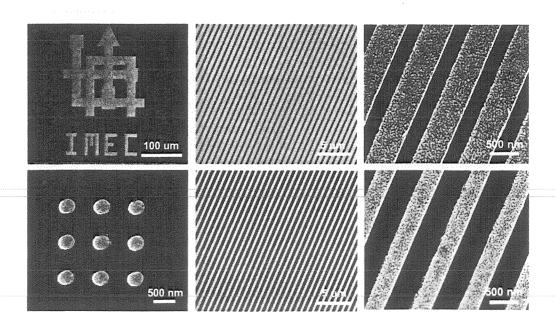


Figure 2. Images of template and UV-NIL stamp. Left: 1 mm<sup>2</sup> and detail of the template and 1 mm<sup>2</sup> and detail of the fabricated stamp. Right: Cross-section image of the fabricated stamp.

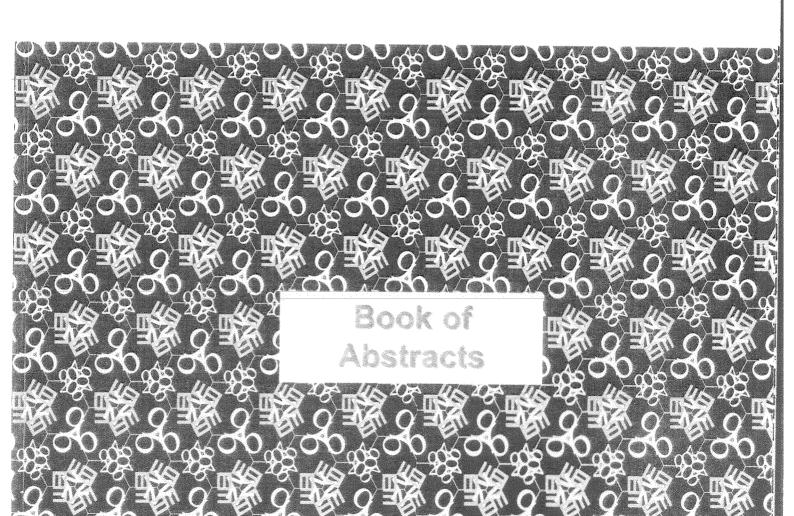


Demonstration of fabricating gold micro- and nanopatterns on top of silicon by UV-NIL using a UV-NIL stamp fabricated with our method. All pictures show parts of one single chip.

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